

# 74HC10-Q100; 74HCT10-Q100

Triple 3-input NAND gate

Rev. 1 — 21 February 2013

Product data sheet

## 1. General description

The 74HC10-Q100; 74HCT10-Q100 is a triple 3-input NAND gate. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD7A
- Input levels:
  - ◆ For 74HC10-Q100: CMOS level
  - ◆ For 74HCT10-Q100: TTL level
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Multiple package options

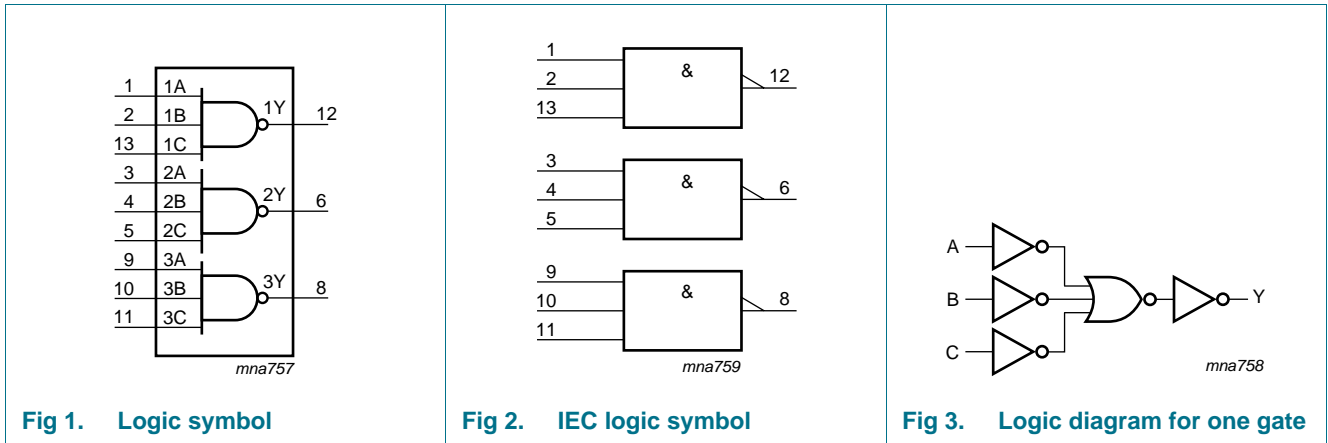
## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC10D-Q100 74HCT10D-Q100	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
74HC10PW-Q100 74HCT10PW-Q100	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1

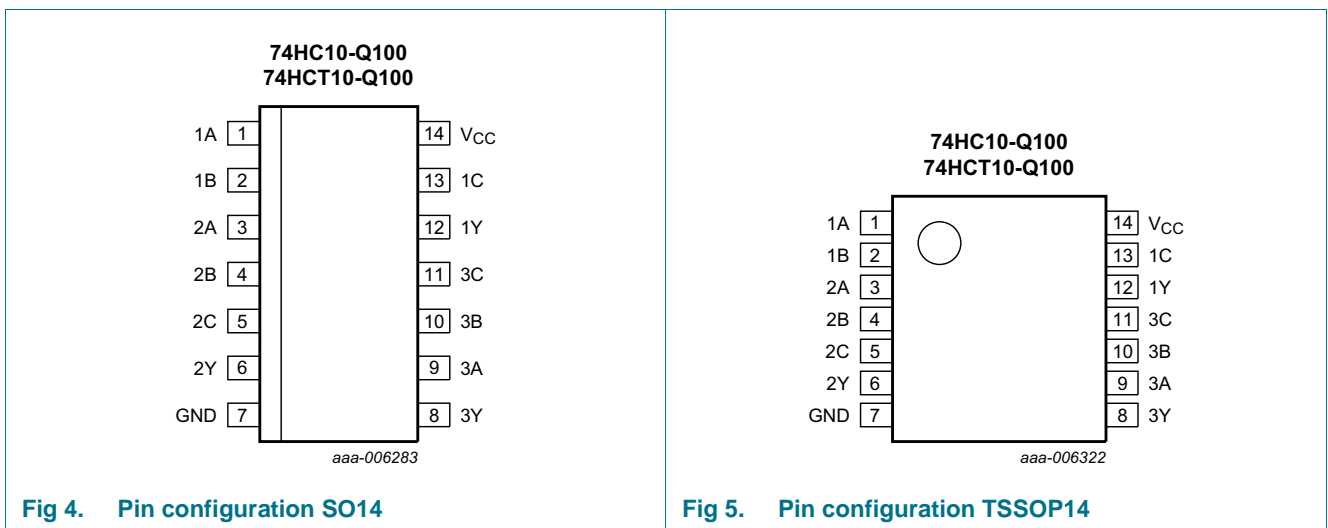


## 4. Functional diagram



## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 2A, 3A	1, 3, 9	data input
1B, 2B, 3B	2, 4, 10	data input
GND	7	ground (0 V)
1C, 2C, 3C	13, 5, 11	data input
1Y, 2Y, 3Y	12, 6, 8	data output
V <sub>CC</sub>	14	supply voltage

## 6. Functional description

Table 3. Function selection<sup>[1]</sup>

Input			Output
nA	nB	nC	nY
L	X	X	H
X	L	X	H
X	X	L	H
H	H	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	[1] -	±20	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	[1] -	±20	mA
$I_O$	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	±25	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	SO14 and TSSOP14 packages	[2] -	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.  
For TSSOP14 package  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	74HC10-Q100			74HCT10-Q100			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC10-Q100</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -5.2 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	2.0	-	20	-	40	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT10-Q100</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 µA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1	-	±1	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	2.0	-	20	-	40	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; I <sub>O</sub> = 0 A; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V	-	150	540	-	675	-	735	µA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**GND = 0 V; C<sub>L</sub> = 50 pF; for test circuit see [Figure 7](#).

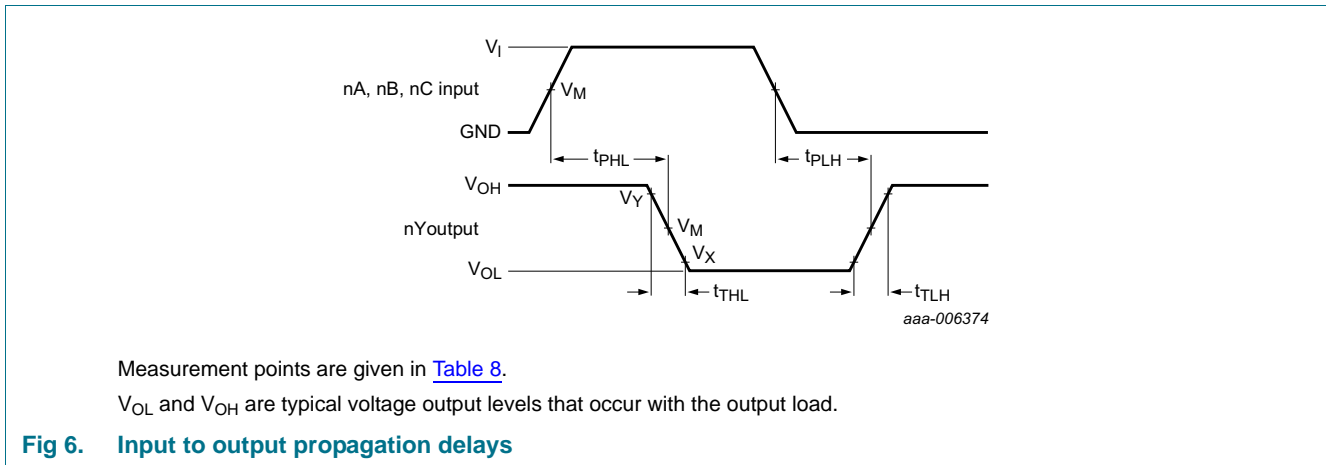
Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C		Unit	
			Min	Typ	Max	Max (85 °C)	Max (125 °C)		
<b>74HC10-Q100</b>									
t <sub>pd</sub>	propagation delay	nA, nB to nY; see <a href="#">Figure 6</a>		<a href="#">[1]</a>					
		V <sub>CC</sub> = 2.0 V	-	30	95	120	145	ns	
		V <sub>CC</sub> = 4.5 V	-	11	19	24	29	ns	
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	9	-	-	-	ns	
t <sub>t</sub>	transition time	see <a href="#">Figure 6</a>		<a href="#">[2]</a>					
		V <sub>CC</sub> = 2.0 V	-	19	75	95	110	ns	
		V <sub>CC</sub> = 4.5 V	-	7	15	19	22	ns	
		V <sub>CC</sub> = 6.0 V	-	6	13	16	19	ns	
C <sub>PD</sub>	power dissipation capacitance	per package; V <sub>I</sub> = GND to V <sub>CC</sub>	<a href="#">[3]</a>	-	12	-	-	-	pF

**Table 7. Dynamic characteristics**  
 GND = 0 V;  $C_L = 50$  pF; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C		Unit	
			Min	Typ	Max	Max (85 °C)	Max (125 °C)		
<b>74HCT10-Q100</b>									
$t_{pd}$	propagation delay	nA, nB to nY; see <a href="#">Figure 6</a>	[1]						
		$V_{CC} = 4.5$ V	-	14	24	30	36	ns	
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	11	-	-	-	ns	
$t_t$	transition time	$V_{CC} = 4.5$ V; see <a href="#">Figure 6</a>	[2]	-	7	15	19	22	ns
$C_{PD}$	power dissipation capacitance	per package; $V_I = GND$ to $V_{CC} - 1.5$ V	[3]	-	14	-	-	-	pF

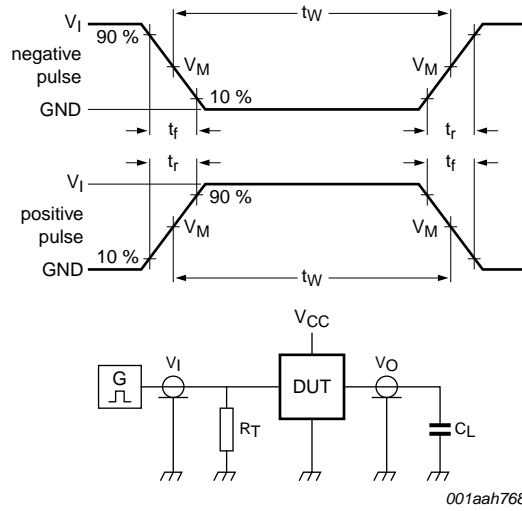
- [1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W):  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 11. Waveform and test circuit



**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74HC10-Q100	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT10-Q100	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



001aah768

Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

**Fig 7. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC10-Q100	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$
74HCT10-Q100	3.0 V	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

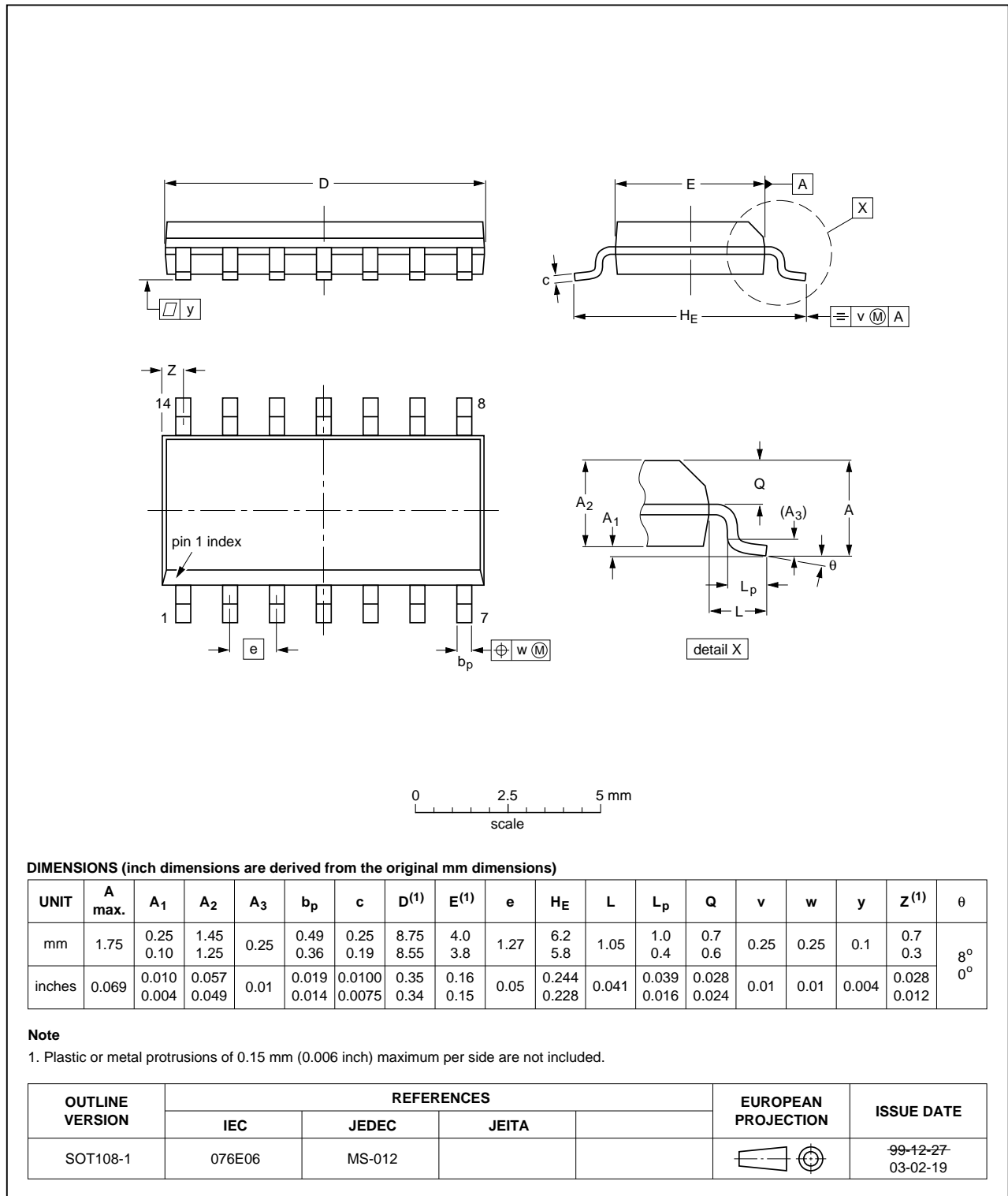


Fig 8. Package outline SOT108-1 (SO14)



TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

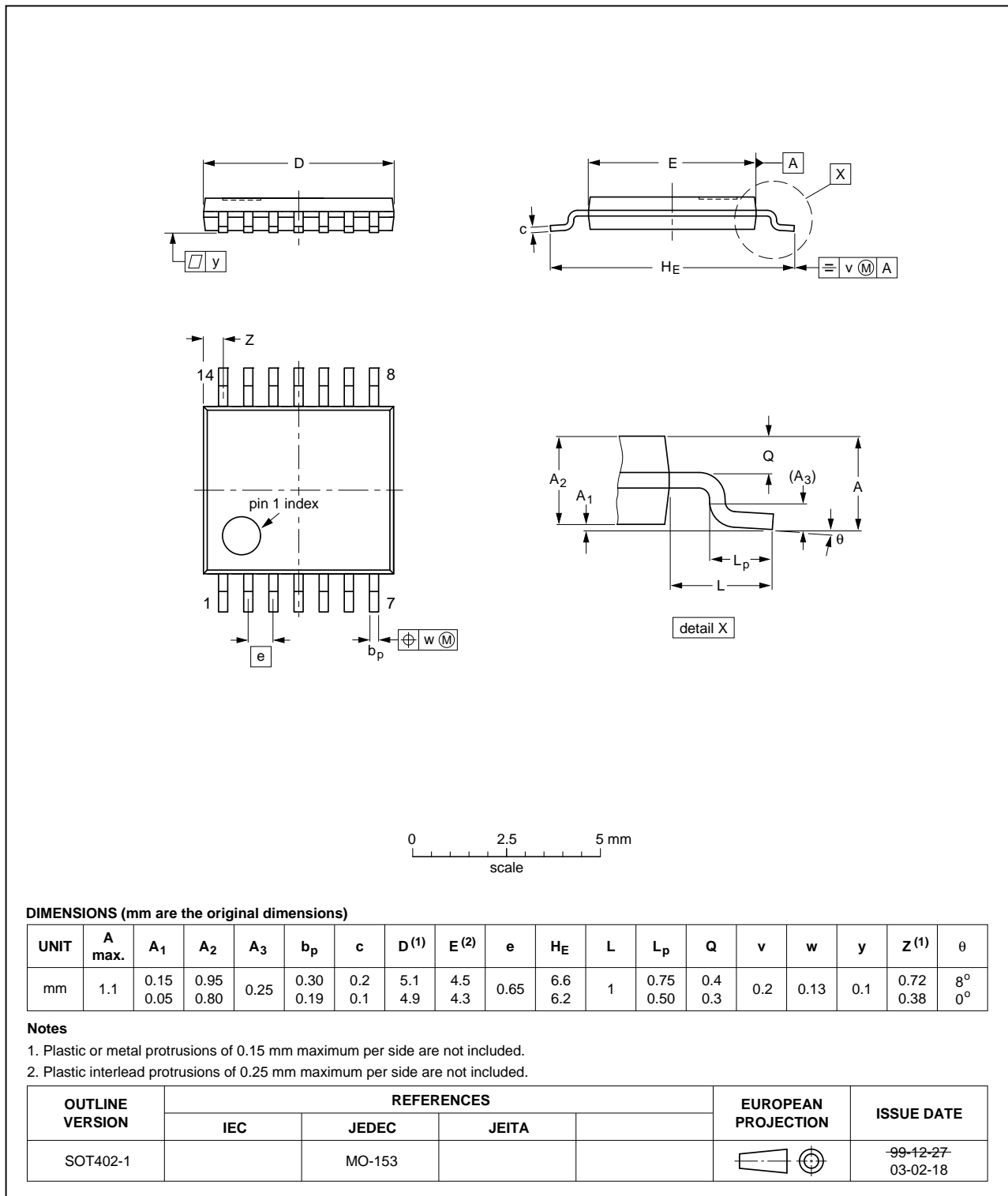


Fig 9. Package outline SOT402-1 (TSSOP14)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT10_Q100 v.1	20130221	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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